

RECOMMENDED SOLDERING CONDITIONS

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Recommended Temperature Profile of Infrared Reflow

Infrared Reflow Soldering

Peak reflow soldering: 235°C

Time of tempature higher than 210°C: 30 seconds or less

Number of reflows: Two

Flux: Rosin flux containing small amount of chorline.
(The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

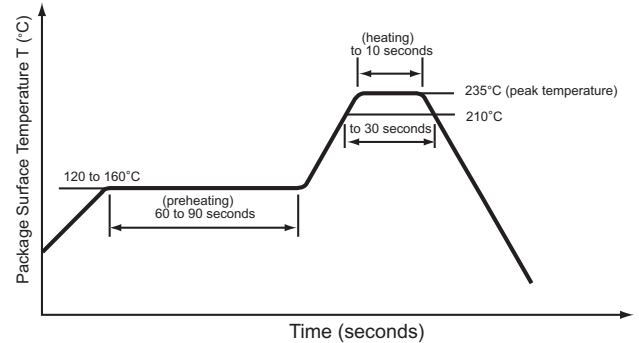
Dip Soldering

Temperature: 260°C or below (molten solder temperature)

Time: 10 seconds or less

Number of times: One

Flux: Rosin flux containing small amount of chorline.
(The flux with a maximum chlorine content of 0.2 Wt% is recommended.)



CAUTION

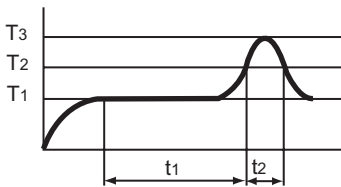
Fluxes: Avoid removing the residual flux with freon-based and chorline-based cleaning solvent.

Products in dry pack: After opening the dry pack, solder the products within the valid storage period specified on the label on the dry pack.

Avoid shorting between portion of frame and leads.

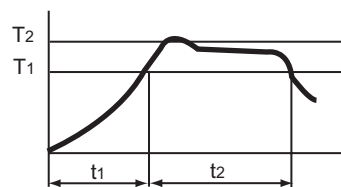
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Infrared Reflow Soldering



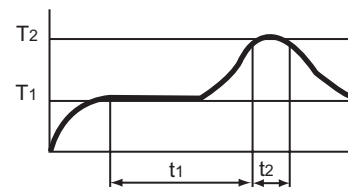
T₁ = 160 to 170°C
T₂ = 160 to 200°C
T₃ = 250°C or less
t₁ = 120 seconds or less
t₂ = 30 seconds or less

Vapor Phase Soldering



T₁ = 180 to 200°C
T₂ = 220°C
t₁ = 40 seconds
t₂ = 90 seconds or less

Double Wave Soldering



T₁ = 160 to 170°C
T₂ = 260°C or less
t₁ = 60 seconds or less
t₂ = 5 seconds or less

Soldering Iron

Tip Temperature: 300°C

Wattage: 30 to 60W

Soldering time: within 5 seconds